

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6404xxxxPR-G

Typical Mass: 57 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|-----------------|------------|------------|
| Silicon chip | 0.757 | Silicon | 13300 | 7440-21-3 |
| | | - Arsenic | <1 | 7440-38-2 |
| Leadframe | 24.392 | Copper | 427900 | 7440-50-8 |
| | | Tin | 300 | 7440-31-5 |
| | | Silver | 3800 | 7440-22-4 |
| Die attach | 0.126 | Silver | 2200 | 7440-22-4 |
| | | Epoxy | 600 | — |
| Bonding wire | 0.116 | Gold | 2000 | 7440-57-5 |
| Resin | 26.730 | Silica | 469000 | 60676-86-0 |
| | | Epoxy resin | 38300 | — |
| | | Phenol resin | 27600 | — |
| | | Metal hydroxide | 7500 | — |
| Plating | 0.430 | Tin | 7500 | 7440-31-5 |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."